

ON Semiconductor®

FDS4465-F085

P-Channel 1.8V Specified PowerTrench MOSFET

General Description

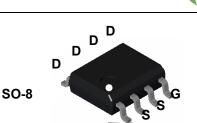
This P-Channel 1.8V specified MOSFET is a rugged gate version of ON Semiconductor's advanced PowerTrench process. It has been optimized for power management applications with a wide range of gate drive voltage (1.8V-8V).

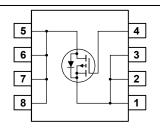
Applications

- Power management
- Load switch
- · Battery protection

Features

- -13.5 A, -20 V. $R_{DS(ON)}$ = 8.5 m Ω @ V_{GS} = -4.5 V $R_{DS(ON)}$ = 10.5 m Ω @ V_{GS} = -2.5 V $R_{DS(ON)}$ = 14 m Ω @ V_{GS} = -1.8 V
- · Fast switching speed
- High performance trench technology for extremely low $R_{\text{DS(ON)}}$
- · High current and power handling capability
- Qualified to AEC Q101
- RoHS Compliant





Absolute Maximum Ratings

T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		-20	V
V _{GSS}	Gate-Source Voltage		±8	V
I _D	Drain Current - Continuous	(Note 1a)	-13.5	Α
	– Pulsed		-50	
P _D	Power Dissipation for Single Operation	(Note 1a)	2.5	W
		(Note 1b)	1.2	
		(Note 1c)	1	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	85	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1c)	125	°C/W
R _{θJC}	Thermal Resistance, Junction-to-Case	(Note 1)	25	°C/W

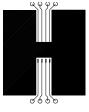
Package Marking and Ordering Information

	- 4.51.6.9	9	9		
Device Marking		Device	Reel Size	Tape width	Quantity
	FDS4465	FDS4465-F085	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics	1	ı	l	l	
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-20			V
<u>ΔBV_{DSS}</u> ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, Referenced to 25°C		-12		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μΑ
I_{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = 8 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -8 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-0.4	-0.6	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = -250 μ A, Referenced to 25°C		3		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	$\begin{split} &V_{GS} = -4.5 \text{ V}, & I_D = -13.5 \text{ A} \\ &V_{GS} = -2.5 \text{ V}, & I_D = -12 \text{ A} \\ &V_{GS} = -1.8 \text{ V}, & I_D = -10.5 \text{ A} \\ &V_{GS} = -4.5 \text{ V}, &I_D = -13.5 \text{A}, &T_J = 125 ^{\circ}\text{C} \end{split}$		6.7 8.0 9.8 9.0	8.5 10.5 14 13	mΩ
I _{D(on)}	On–State Drain Current	$V_{GS} = -4.5 \text{ V}, V_{DS} = -5 \text{ V}$	-50			Α
g _{FS}	Forward Transconductance	$V_{DS} = -5 \text{ V}, \qquad I_{D} = -13.5 \text{ A}$		70		S
Dynamic	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}.$		8237		pF
Coss	Output Capacitance	f = 1.0 MHz		1497		pF
C _{rss}	Reverse Transfer Capacitance			750		pF
Switchin	g Characteristics (Note 2)					
t _{d(on)}	Turn–On Delay Time	$V_{DD} = -10V$, $I_{D} = -1 A$,		20	36	ns
t _r	Turn-On Rise Time	$V_{GS} = -4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		24	38	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time	1		300	480	ns
t _f	Turn-Off Fall Time			140	224	ns
Qg	Total Gate Charge	$V_{DS} = -10 \text{ V}, \qquad I_{D} = -13.5 \text{ A},$		86	120	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = -4.5 \text{ V}$		20		nC
Q_{gd}	Gate-Drain Charge	1		11		nC
Drain-S	ource Diode Characteristics	and Maximum Ratings				
Is	Maximum Continuous Drain–Source				-2.1	Α
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = -2.1 \text{ A} \text{(Note 2)}$		-0.6	-1.2	V

Notes

 R_{8JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{8JC} is guaranteed by design while R_{8CA} is determined by the user's board design.



a) 50 °C/W when mounted on a 1in² pad of 2 oz copper



b) 105 °C/W when mounted on a 04 in² pad of 2 oz copper



c) 125 °C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

Typical Characteristics

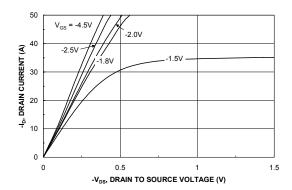


Figure 1. On-Region Characteristics.

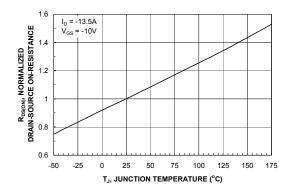


Figure 3. On-Resistance Variation with Temperature.

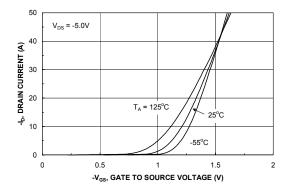


Figure 5. Transfer Characteristics.

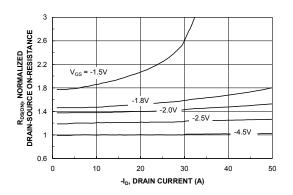


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

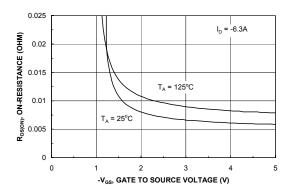


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

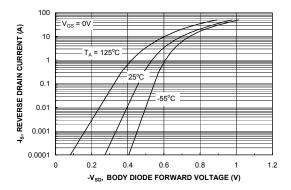
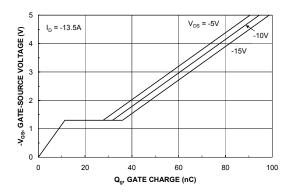


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



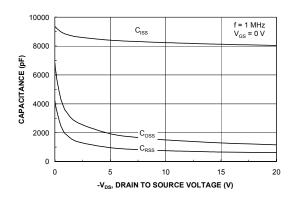
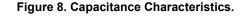
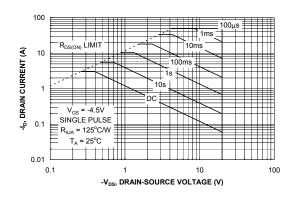


Figure 7. Gate Charge Characteristics.





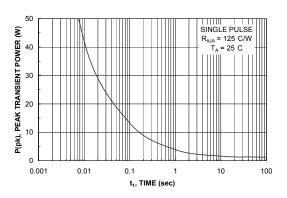


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

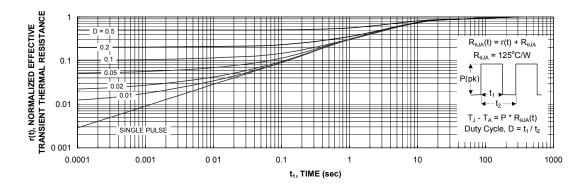


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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